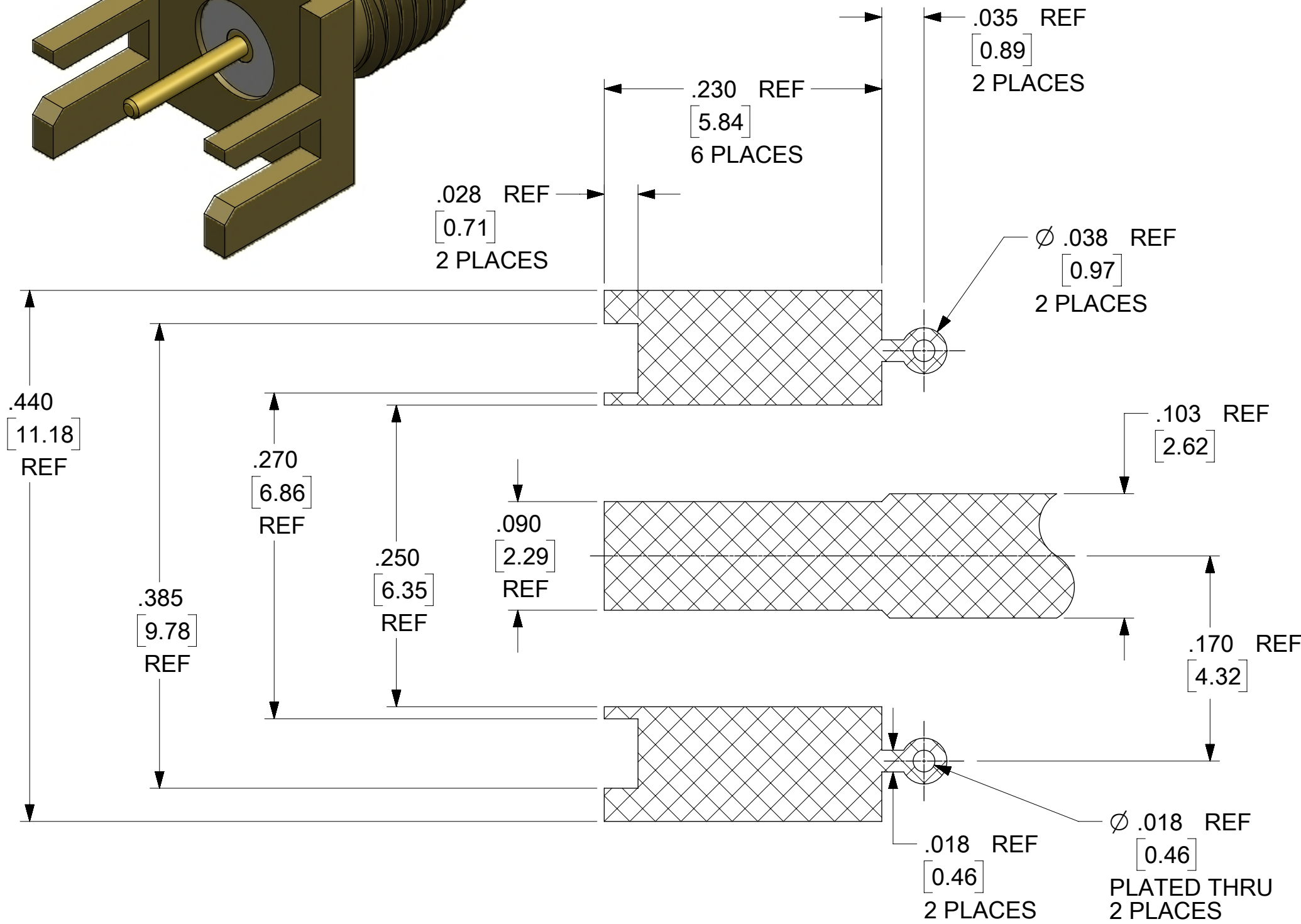
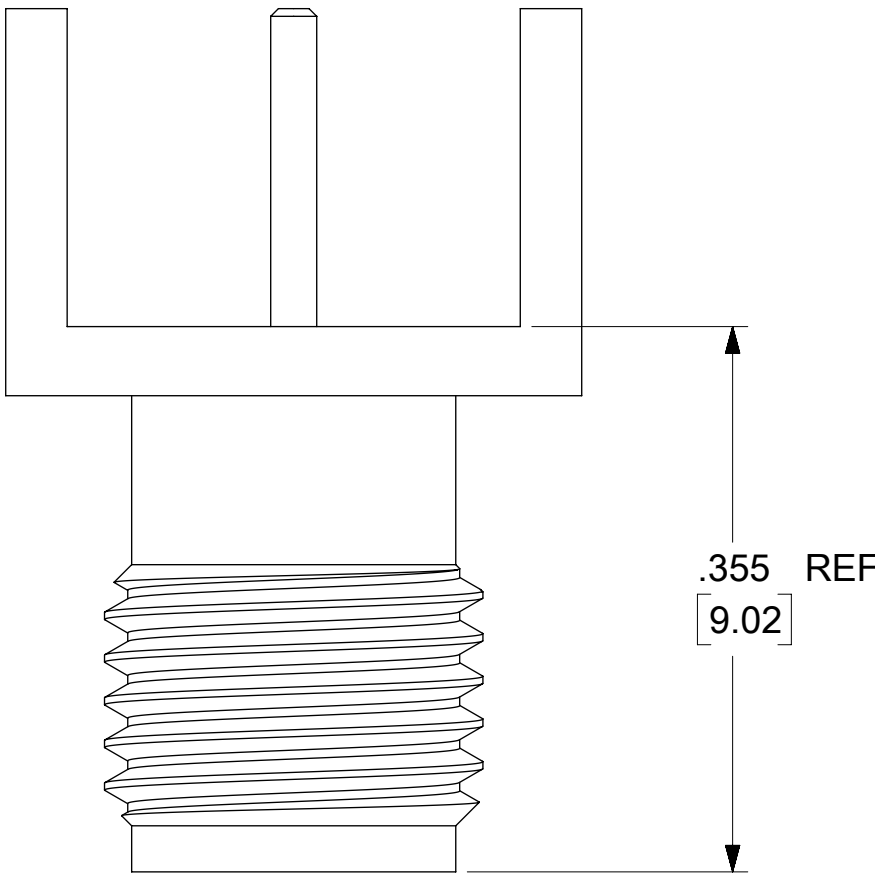
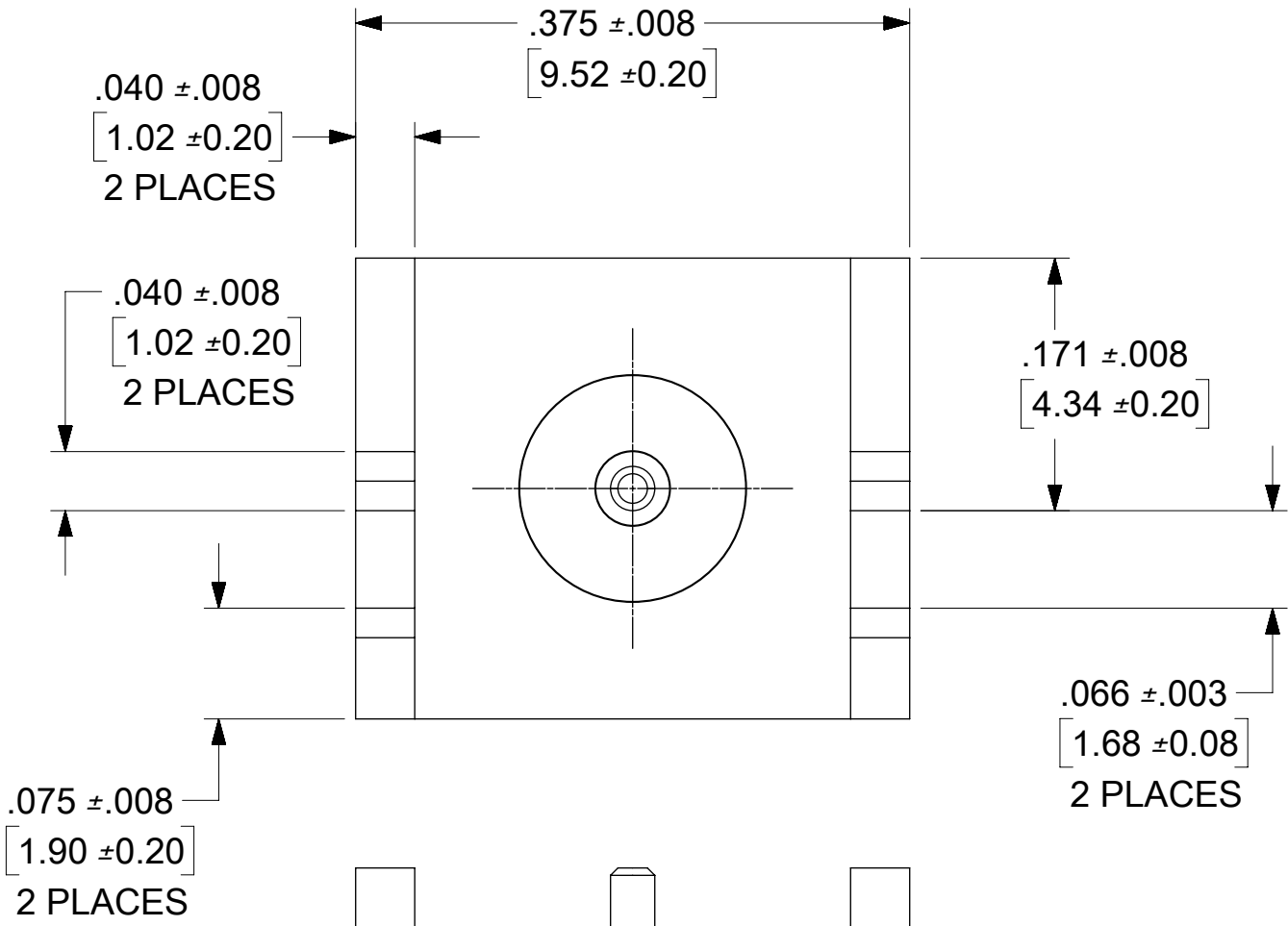
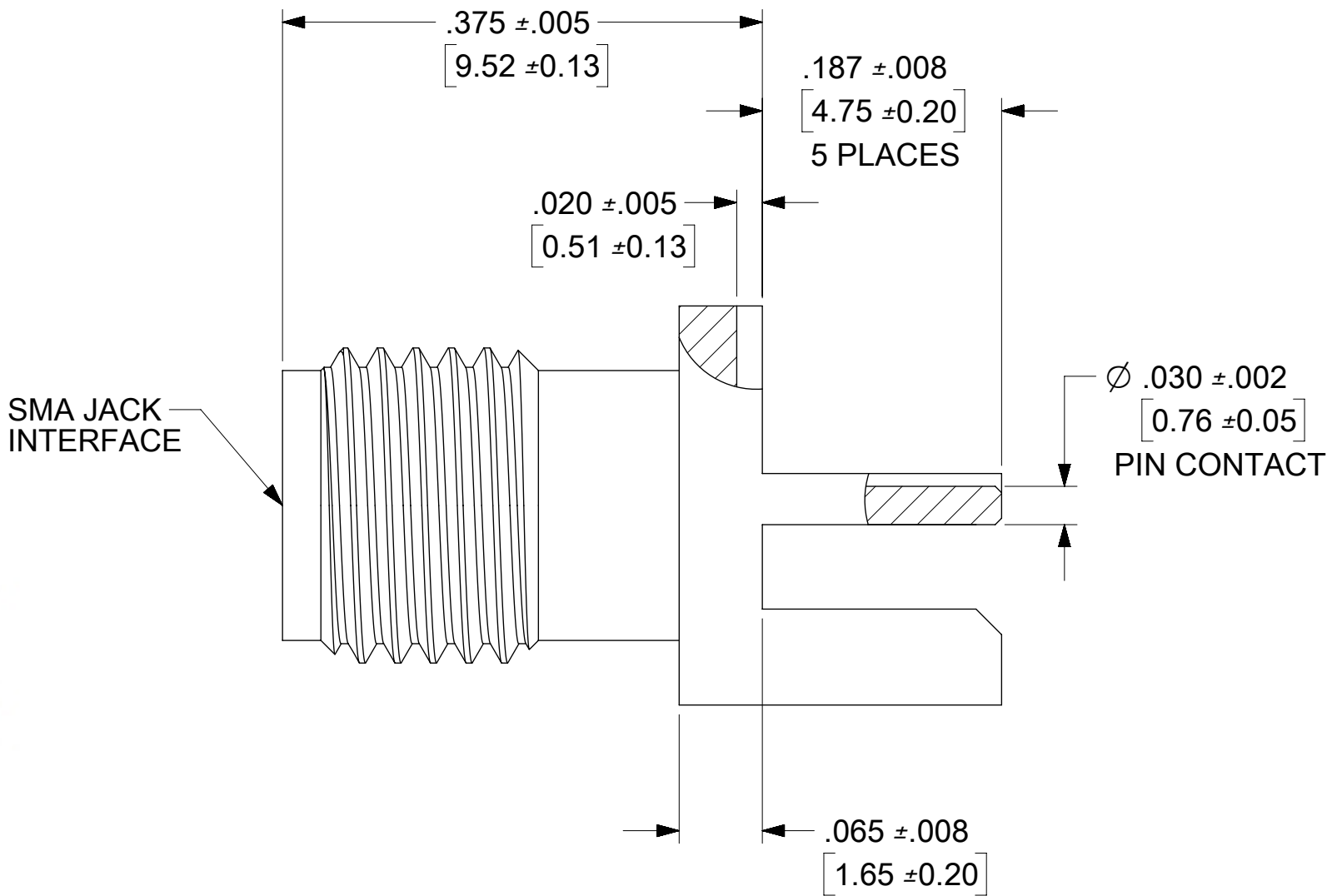
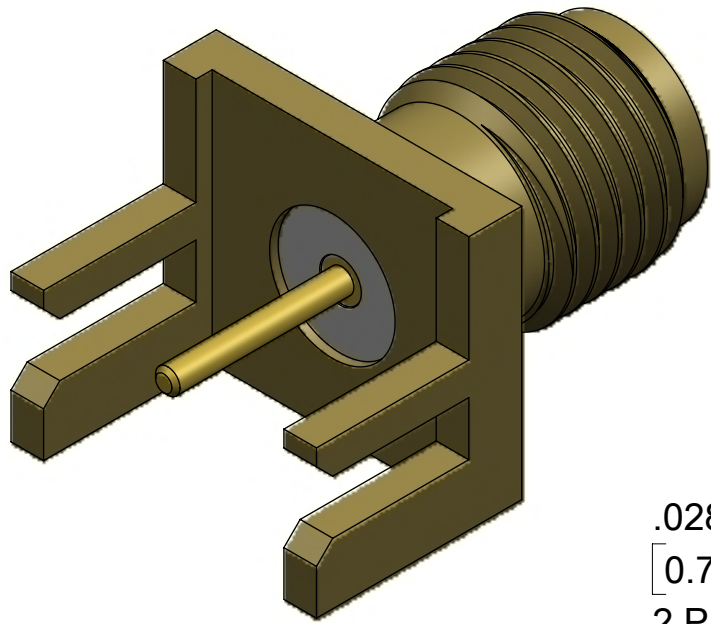
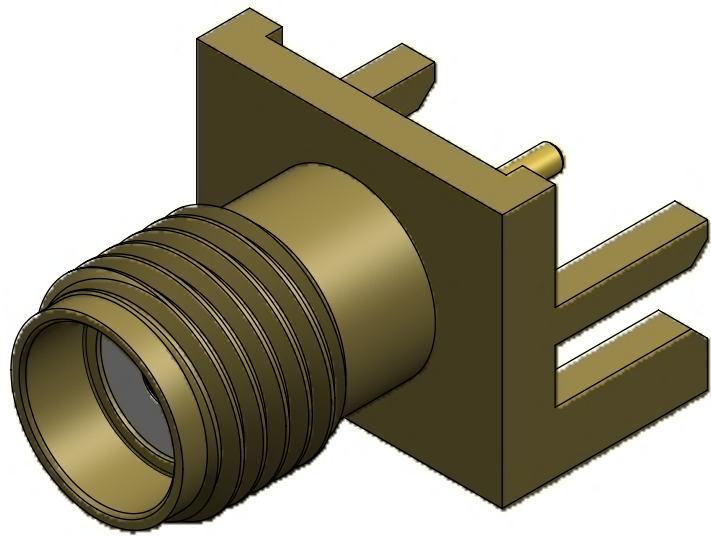


MATERIALS AND FINISHES

BODY: BRASS
PLATED GOLD (SEE TABLE)

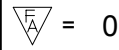
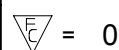
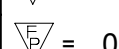
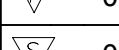
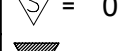
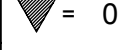
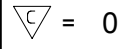
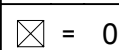
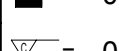
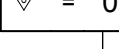
CENTER CONTACT: BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR: PTFE



PCB PAD (FOR REFERENCE ONLY)

BOARD THICKNESS: $.062$ [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER
ON BOTTOM (GROUND) SIDE

73251-1153	GOLD (1μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (5μ-in MIN) OVER NICKEL (50μ-in MIN)	TRAY (80 PIECES)
73251-1152	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (20 PIECES)
73251-1151	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	ONE 73251-1150 PER BAG
73251-1150	GOLD (10μ-in MIN) OVER NICKEL (50μ-in MIN)	GOLD (10μ-in MIN) OVER NICKEL (100μ-in MIN)	TRAY (80 PIECES)
PART NO.	BODY	CONTACT	DESCRIPTION
	PLATING		PACKAGING
SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
 = 0	DIMENSION UNITS	SCALE	CURRENT REV DESC: SEE ECM
 = 0	INCH	NTS	
 = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 172847 DRWN: LMEIER 2018/02/23 CHK'D: SSSHAH 2018/03/01 APPR: AROBERTSON 2018/03/01 INITIAL REVISION:
 = 0		MM	
 = 0		INCH	DRWN: TEF 2002/06/27 APPR: GMH 2002/06/27
 = 0	4 PLACES $\pm$	$\pm$	
 = 0	3 PLACES $\pm$	$\pm$ 0.005	THIRD ANGLE PROJECTION
 = 0	2 PLACES $\pm$ 0.13	$\pm$ 0.01	
 = 0	1 PLACE $\pm$ 0.25	$\pm$	DRAWING C-SIZE
 = 0	0 PLACES $\pm$	$\pm$	
 = 0	ANGULAR TOL $\pm$ 2.0 °		SERIES 73251
 = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NUMBER
= 0			CUSTOMER
			SHEET NUMBER

PS-89675-3460		PRODUCT SPECIFICATION	
MIL-STD-348B, FIG. 310-2		INTERFACE	
SPECIFICATION		DESCRIPTION	
DOCUMENT STATUS	P1	RELEASE DATE	2018/03/01 20:38:20